

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT4957822

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TAHIR CADER	05/08/2018
HARVEY LUNSMAN	04/26/2018
ERNESTO FERRER MEDINA	04/26/2018
JOHN FRANZ	05/08/2018
RECEIVING PARTY DATA	
Name:	Hewlett Packard Enterprise Development LP
Street Address:	11445 Compaq Center Drive West
City:	Houston
State/Country:	TEXAS
Postal Code:	77070
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15974798
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(970) 898-7472
Email:	hpe.ip.mail@hpe.com
Correspondent Name:	HEWLETT PACKARD ENTERPRISE
Address Line 1:	3404 E. HARMONY ROAD MS 79
Address Line 4:	FORT COLLINS, COLORADO 80528
ATTORNEY DOCKET NUMBER:	90545580
NAME OF SUBMITTER:	MARILEE JENSON
SIGNATURE:	/Marilee Jenson/
DATE SIGNED:	05/11/2018
Total Attachments: 4	
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Hewlett Packard Enterprise
3404 E. Harmony Road
Mail Stop 79
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID: 90545580

ASSIGNMENT OF PATENT APPLICATION

I/We, the undersigned (each), for good and valuable consideration, the receipt of which is hereby acknowledged, and in furtherance of my/our obligations to Hewlett Packard Enterprise Development LP, a Texas Limited Partnership having its principal place of business in Houston, Texas, (hereinafter HPED), and to its subsidiaries and affiliates, agree to assign and transfer and hereby assign and transfer to HPED, its successors and assigns, the entire right, title and interest, including the right of priority, in, to and under an application for Patent entitled:

CONDUCTING PLASTIC COLD PLATES

Filing Date: _____ Application No.: _____

and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (C-I-P's), divisionals, and renewals of and substitutes for said application for said Patent, and any and all other Patent of any countries thereto which may be granted thereon or therefore; and any reissues, or reexaminations, or extensions of said Patent.

I/we additionally authorize HPED to file applications in my/our name for Patent in any country, to be held and enjoyed by HPED, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by me/us had this assignment, and transfer not been made;

AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said application and said Patent, to HPED, its successors, assigns, nominees or legal representatives, and I/we agree to communicate to HPED, or to its nominee, all known facts respecting said invention(s) or improvement(s), said application and said Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-I-P's, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid HPED, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by HPED;

AND I/we hereby authorize and request the official of any country or countries whose duty it is to issue patents on applications as aforesaid, to issue to HPED, as assignee of the entire right, title and interest, any and all Patent for said invention(s) or improvement(s) which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

I/we further authorize and direct the attorneys of record to insert the filing date and application number of said application for Patent, now identified by the Record ID and title set forth above, as soon as the same shall have been made known to them.

IN WITNESS WHEREOF, I/we hereunto set my/our hand(s) and seal(s):

Tahir Cader _____ Date 5/8/18

Tahir Cader

First/Middle Name/Last Name

Inventor's Signature Date

Harvey Lunsman

First/Middle Name/Last Name

Hewlett Packard Enterprise
3404 E. Harmony Road
Mail Stop 79
Fort Collins, Colorado 80528

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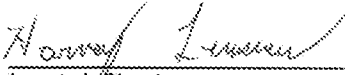
IN WITNESS WHEREOF, I/we hereunto set my/our hand(s) and seal(s):

Inventor's Signature

Date

Tahir Cader

First/Middle Name/Last Name



Inventor's Signature

4/26/2018

Date

Harvey Lunsman

First/Middle Name/Last Name

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3404 E. Harmony Road
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PATENT APPLICATION

RECORD ID: 90545580

ASSIGNMENT OF PATENT APPLICATION (cont.)

EM _____ Date 4/26/2018
Inventor's Signature _____ Date

Ernesto Ferrer Medina
First/Middle Name/Last Name _____

Inventor's Signature _____ Date

John Franz
First/Middle Name/Last Name _____

Inventor's Signature _____ Date *

First/Middle Name/Last Name _____

Inventor's Signature _____ Date

First/Middle Name/Last Name _____

Inventor's Signature _____ Date

First/Middle Name/Last Name _____

Inventor's Signature _____ Date

First/Middle Name/Last Name _____

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PATENT APPLICATION

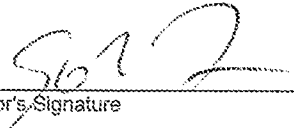
RECORD ID: 90545580

ASSIGNMENT OF PATENT APPLICATION (cont.)

Inventor's Signature _____ Date _____

Ernesto Ferrer Medina

First/Middle Name/Last Name

 _____
Inventor's Signature _____ Date 5-8-2018

John Franz

First/Middle Name/Last Name

Inventor's Signature _____ Date _____

First/Middle Name/Last Name

Inventor's Signature _____ Date _____

First/Middle Name/Last Name

Inventor's Signature _____ Date _____

First/Middle Name/Last Name

Inventor's Signature _____ Date _____

First/Middle Name/Last Name